

Diffusion

Diffusion - Mass transport by atomic motion

Mechanisms

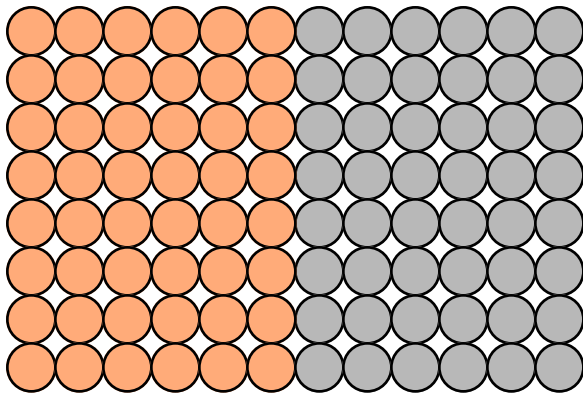
- Gases & Liquids – random (Brownian) motion
- Solids – vacancy diffusion or interstitial diffusion

Interdiffusion: In an alloy, atoms tend to migrate from regions of high conc. to regions of low conc.

Self-diffusion: In an elemental solid, atoms also migrate.

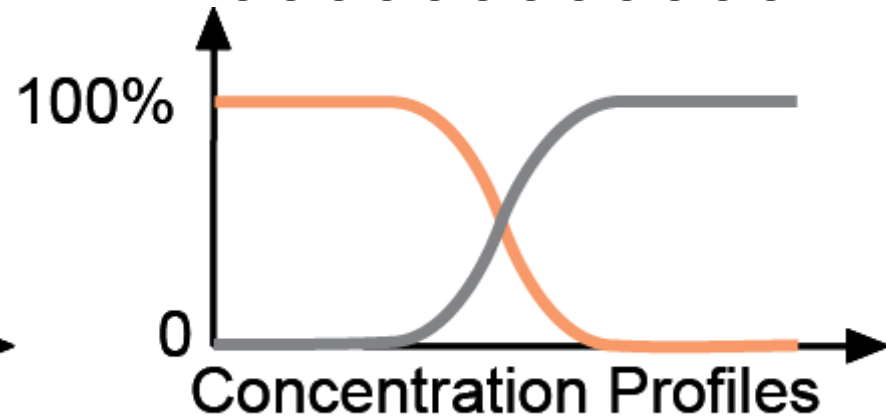
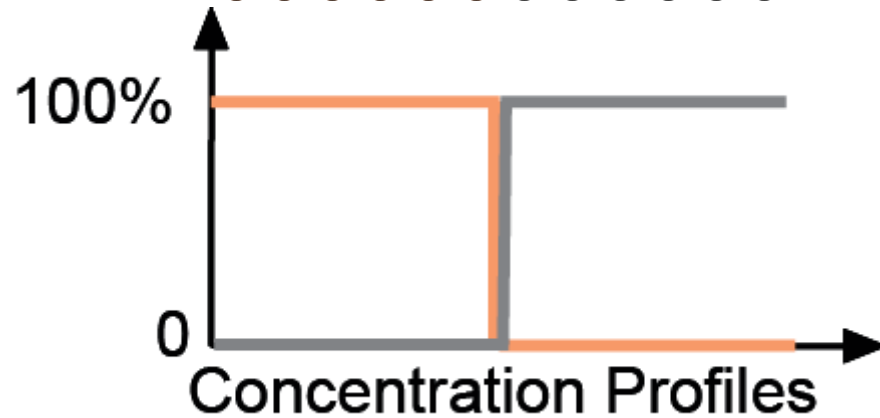
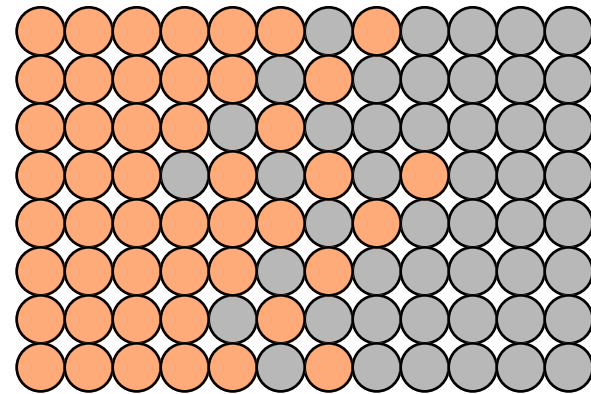
Interdiffusion

Initially



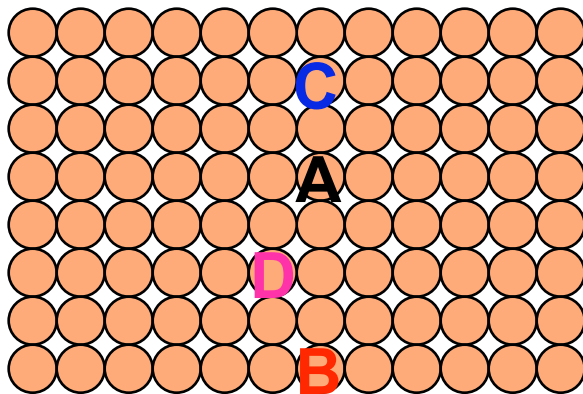
Adapted from
Figs. 5.1 and
5.2, *Callister*
7e.

After some time

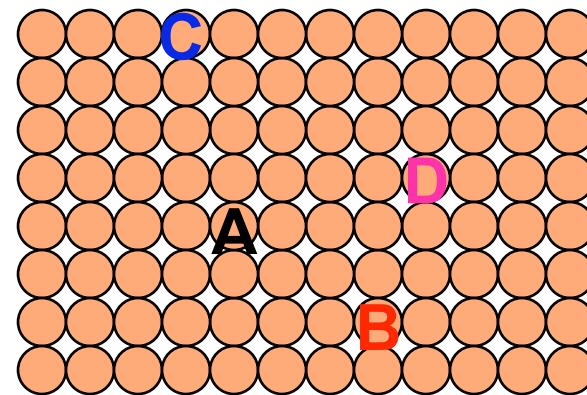


Self-diffusion

Label some atoms



After some time

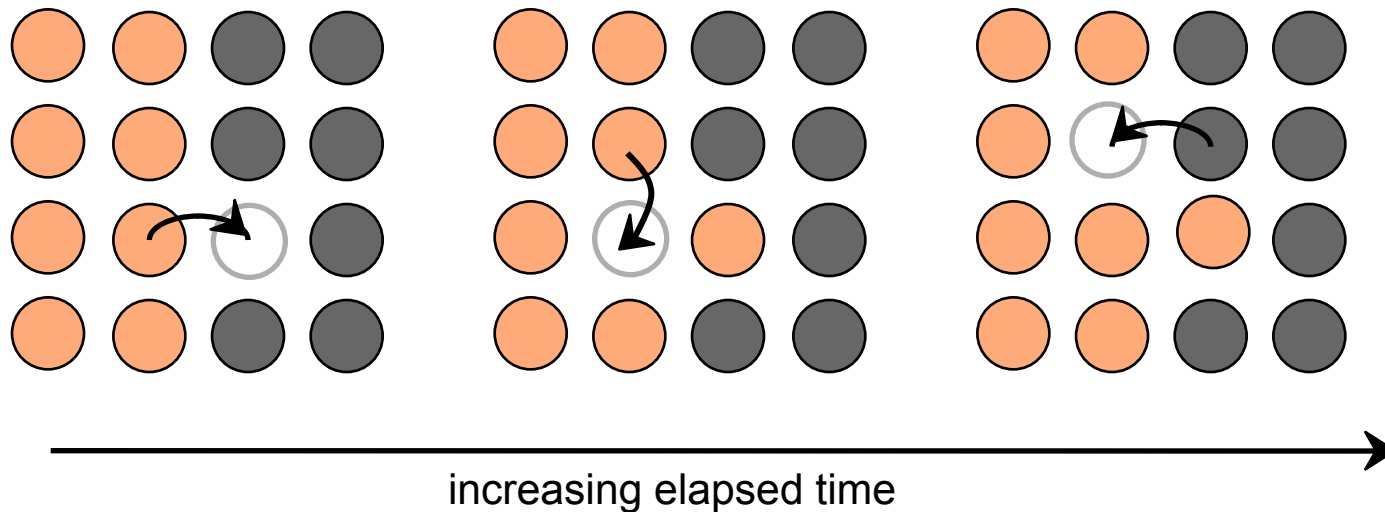


Diffusion mechanisms

Conditions:

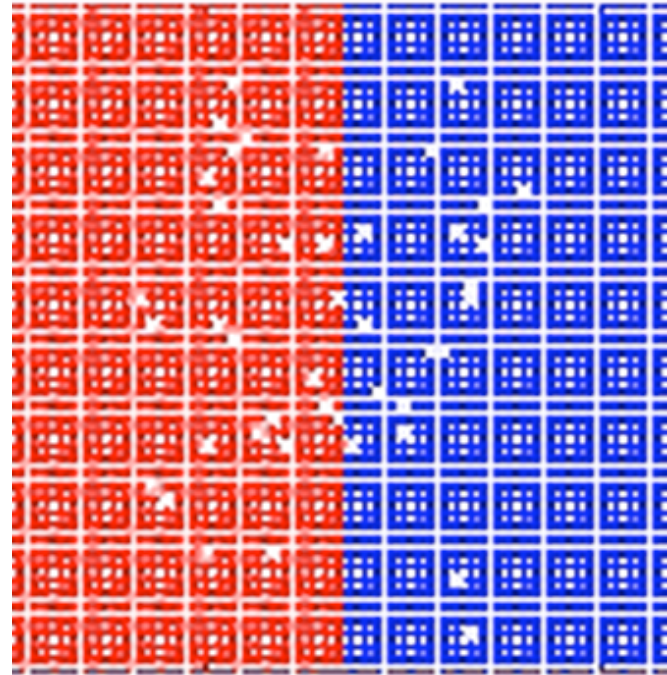
Vacancy Diffusion:

- atoms exchange with vacancies
- applies to substitutional impurities atoms
- rate depends on:
 - number of vacancies
 - activation energy to exchange.



Diffusion simulation

- Simulation of interdiffusion across an interface:
- Rate of substitutional diffusion depends on:
 - vacancy concentration
 - frequency of jumping.



(Courtesy P.M. Anderson)

Diffusion flux

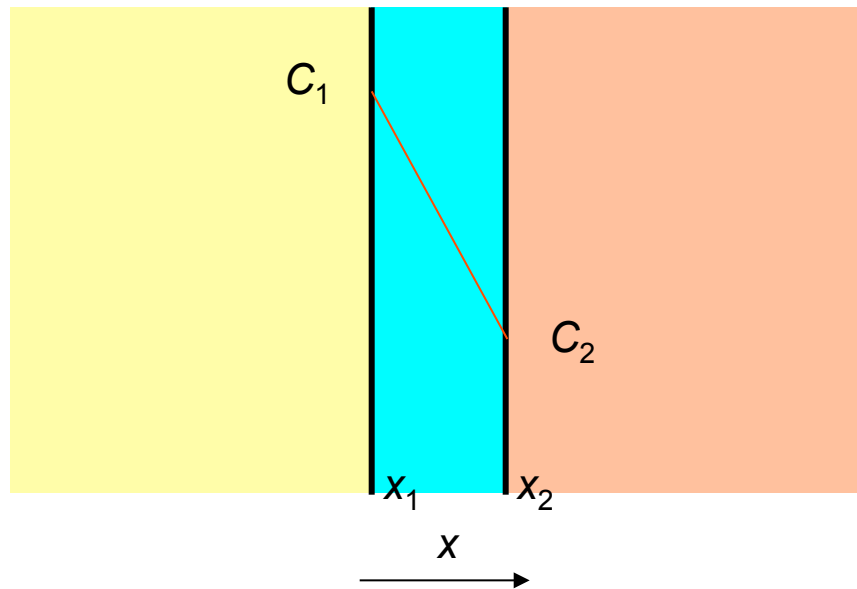
How do we quantify the amount or rate of diffusion?

Measured empirically

- Make thin film (membrane) of known surface area
- Impose concentration gradient
- Measure how fast atoms or molecules diffuse through the membrane

Steady-state diffusion

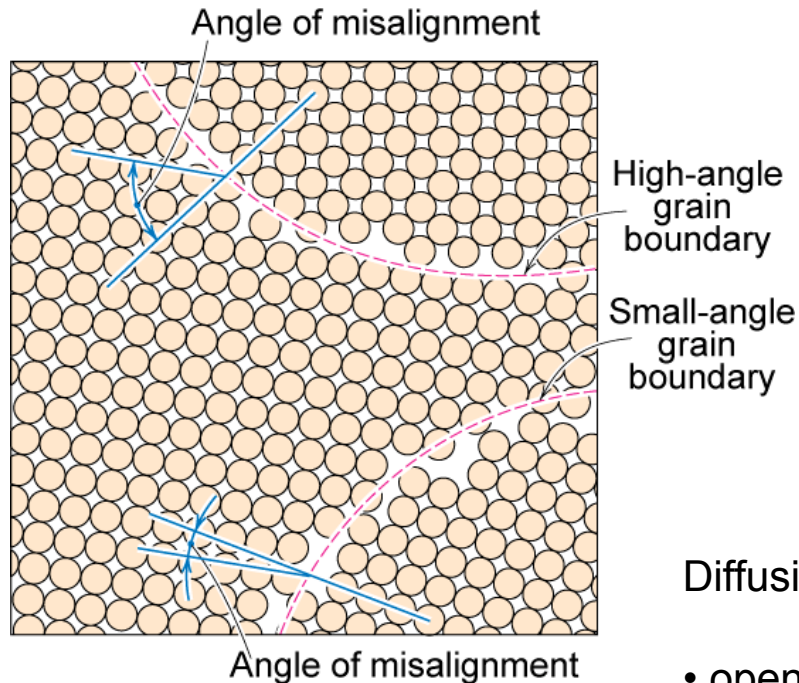
Flux proportional to concentration gradient = $\frac{dC}{dx}$



Diffusion and temperature

- Diffusion coefficient increases with increasing T .

Diffusion paths



Diffusion **FASTER** for...

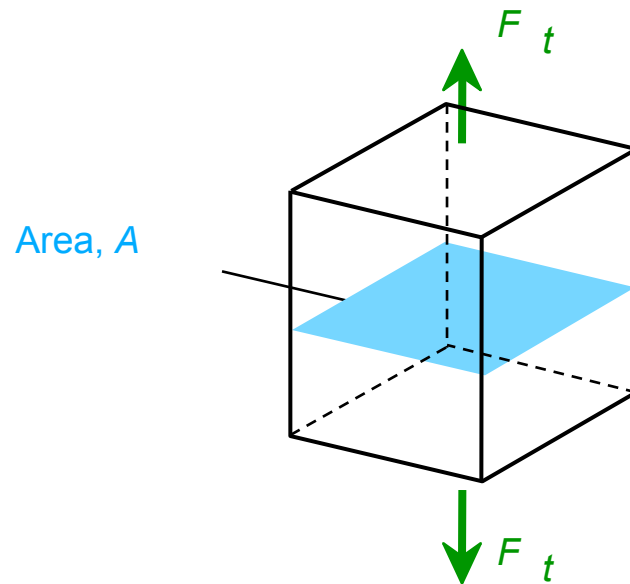
- open crystal structures
- materials w/secondary bonding
- smaller diffusing atoms
- lower density materials

Diffusion **SLOWER** for...

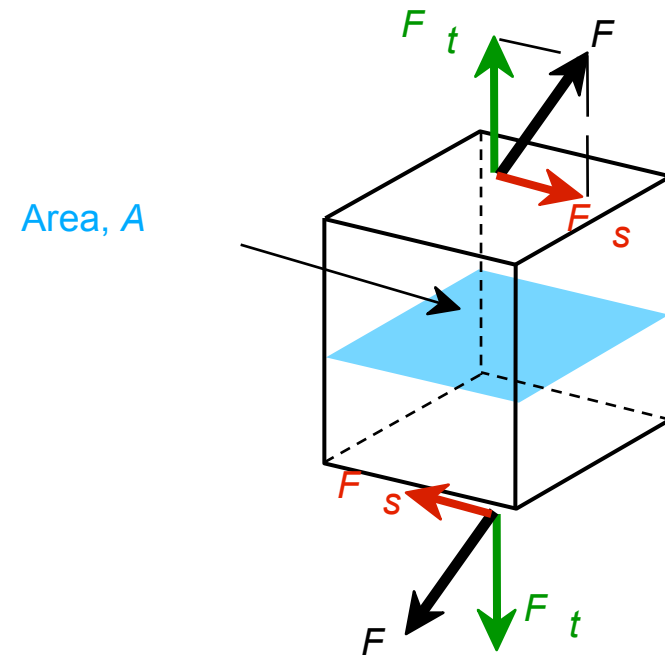
- close-packed structures
- materials w/covalent bonding
- larger diffusing atoms
- higher density materials

Engineering stress

- Tensile stress, σ :



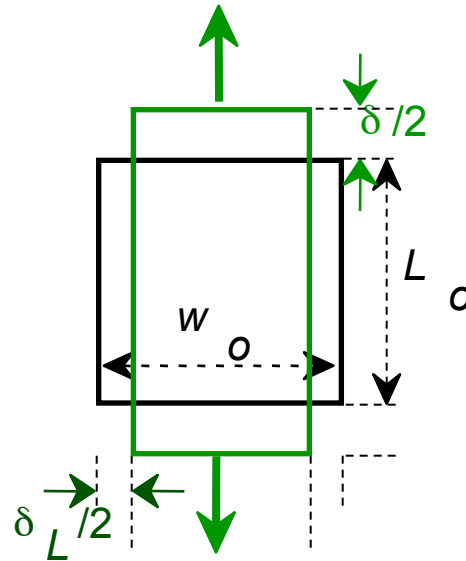
- Shear stress, τ :



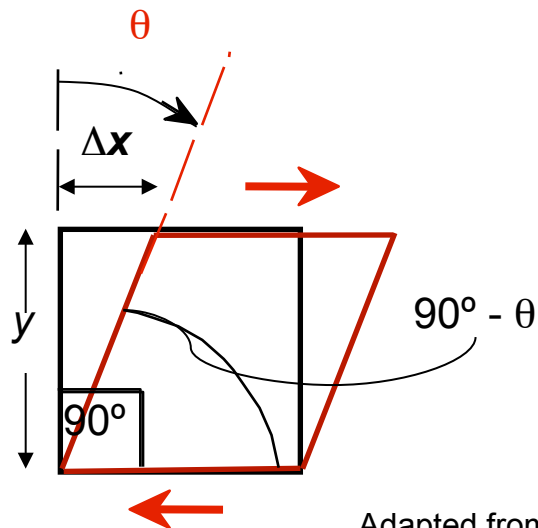
Engineering strain

- **Tensile strain:**

- **Lateral strain:**



- **Shear strain:**

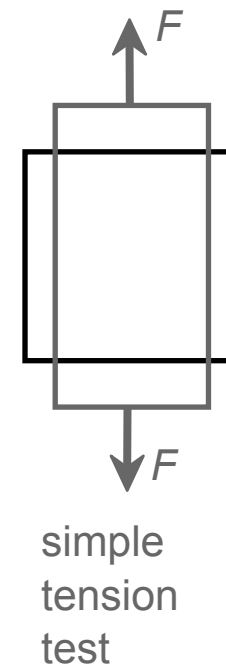
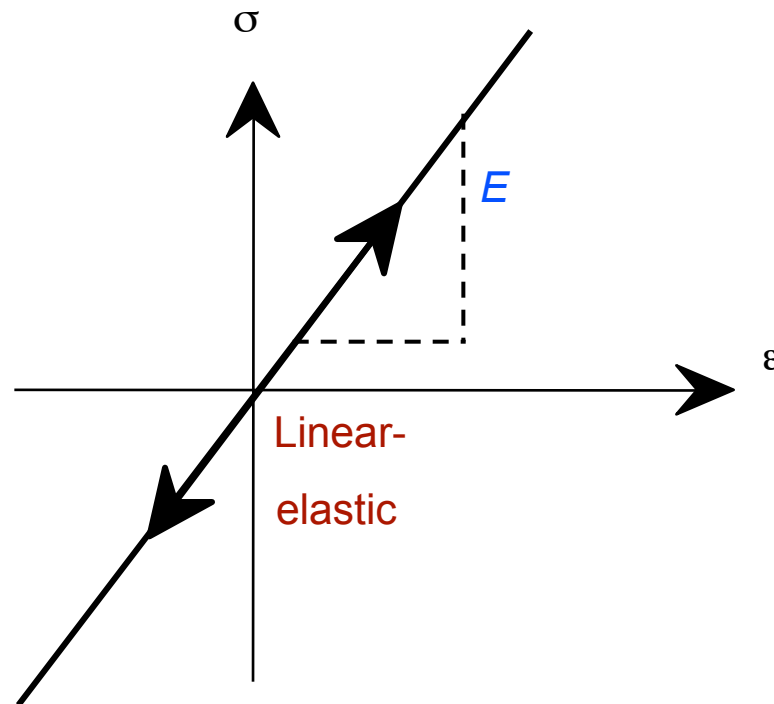


$$\gamma = \Delta x / y = \tan \theta$$

Adapted from Fig. 6.1 (a) and (c), *Callister 7e*.

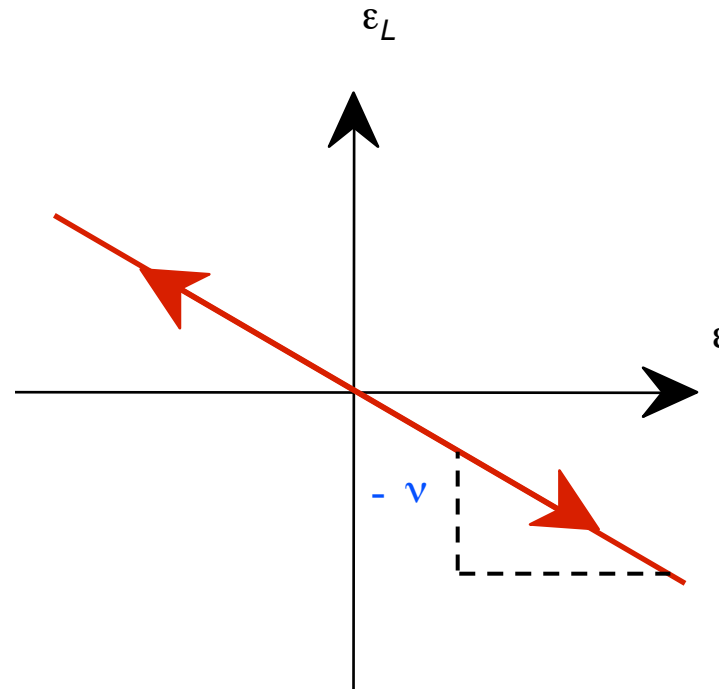
Engineering strain

- **Modulus of Elasticity, E :**
(also known as Young's modulus)



Elastic properties of materials

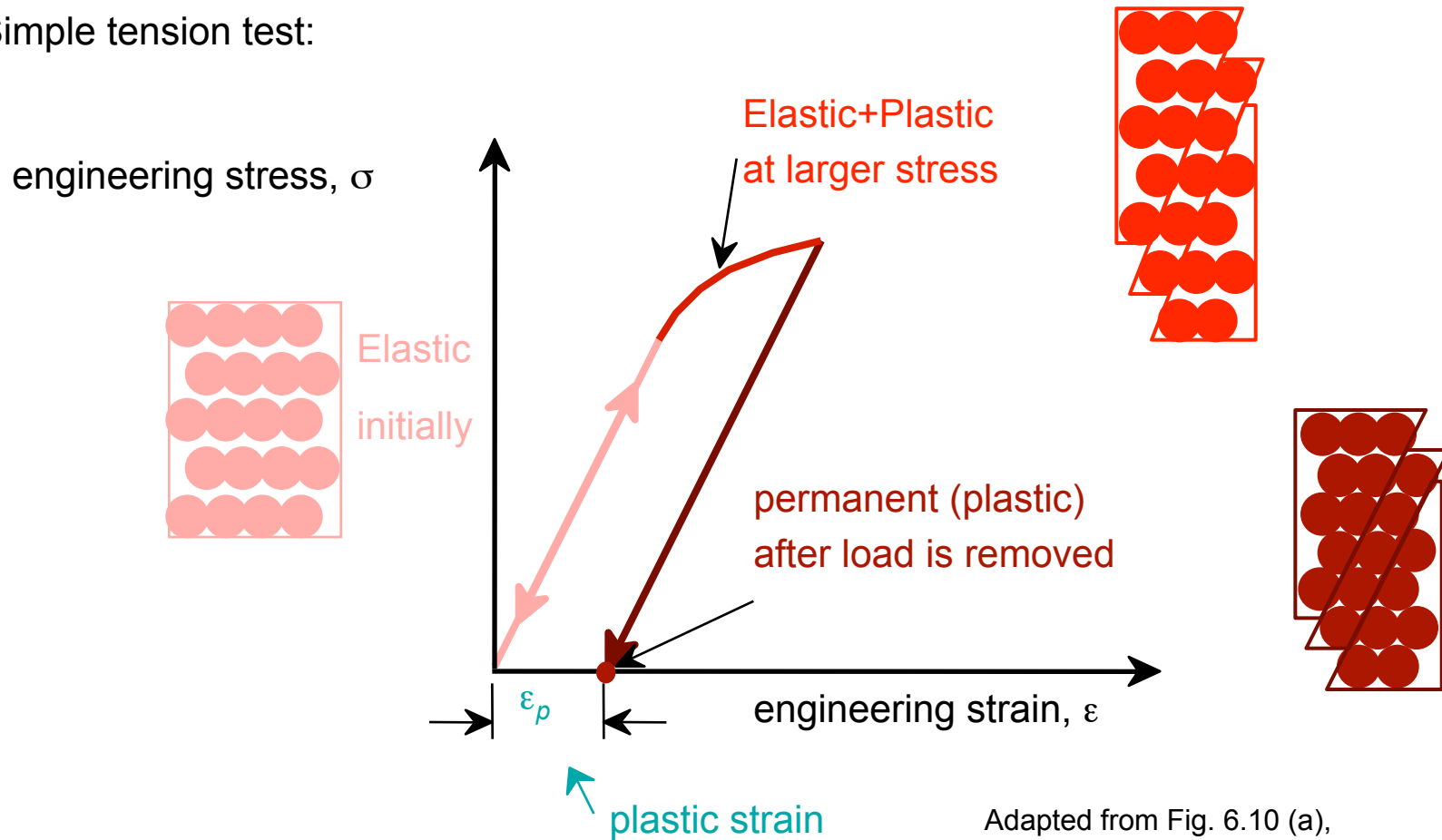
- Poisson's ratio, ν :



- $-\nu > 0.50$ density increases
- $-\nu < 0.50$ density decreases
(voids form)

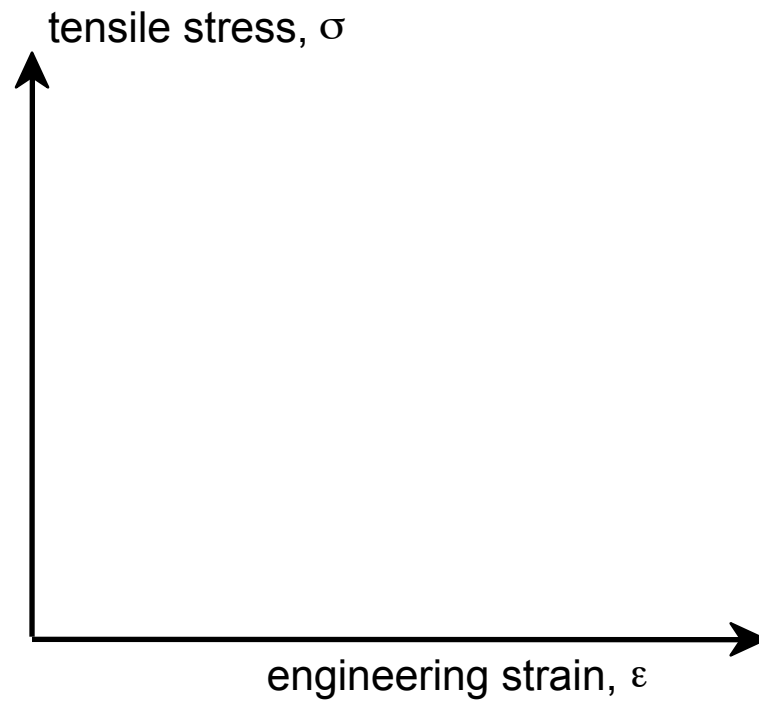
Plastic deformation

- Simple tension test:



Adapted from Fig. 6.10 (a),
Callister 7e.

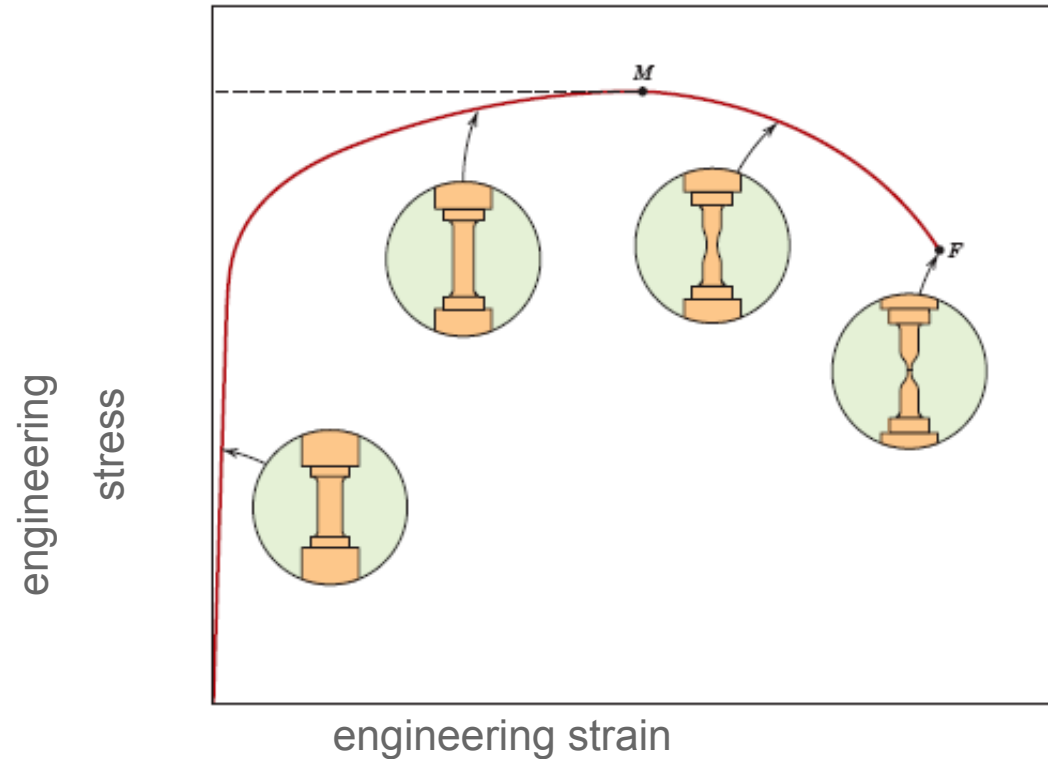
Yield strength, σ_y



Adapted from Fig. 6.10 (a),
Callister 7e.

Tensile strength, TS

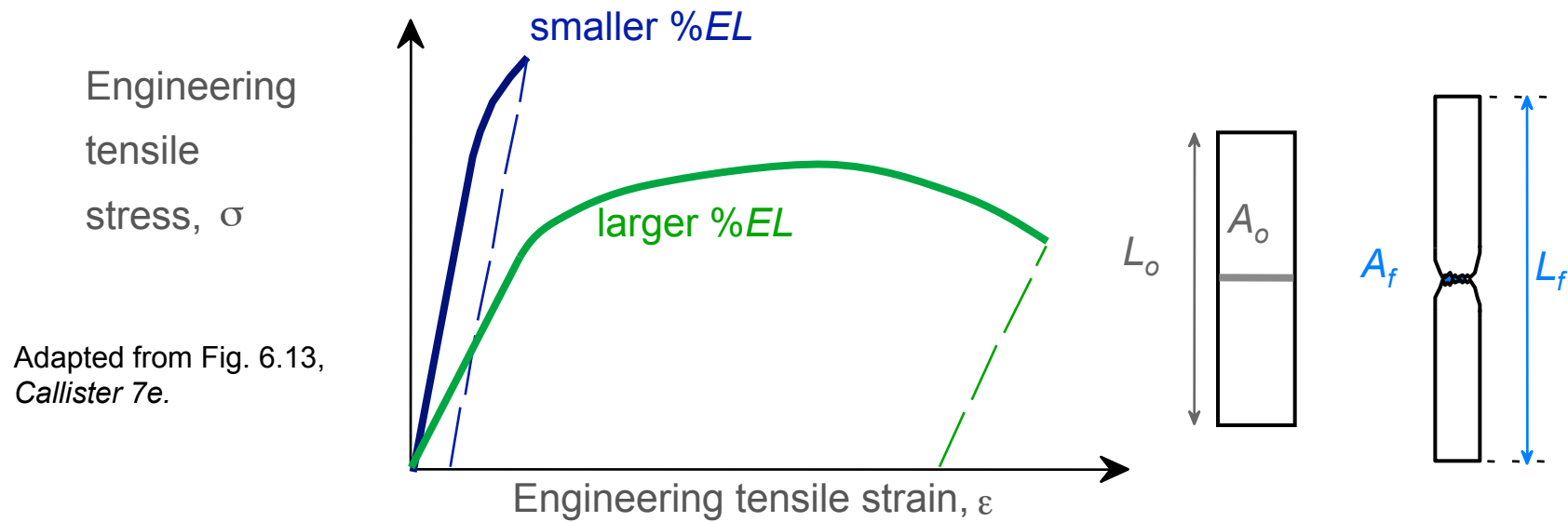
- Maximum stress on engineering stress-strain curve.



- **Metals**: occurs when noticeable **necking** starts.
- **Polymers**: occurs when **polymer backbone chains** are aligned and about to break.

Ductility

- Plastic tensile strain at failure:

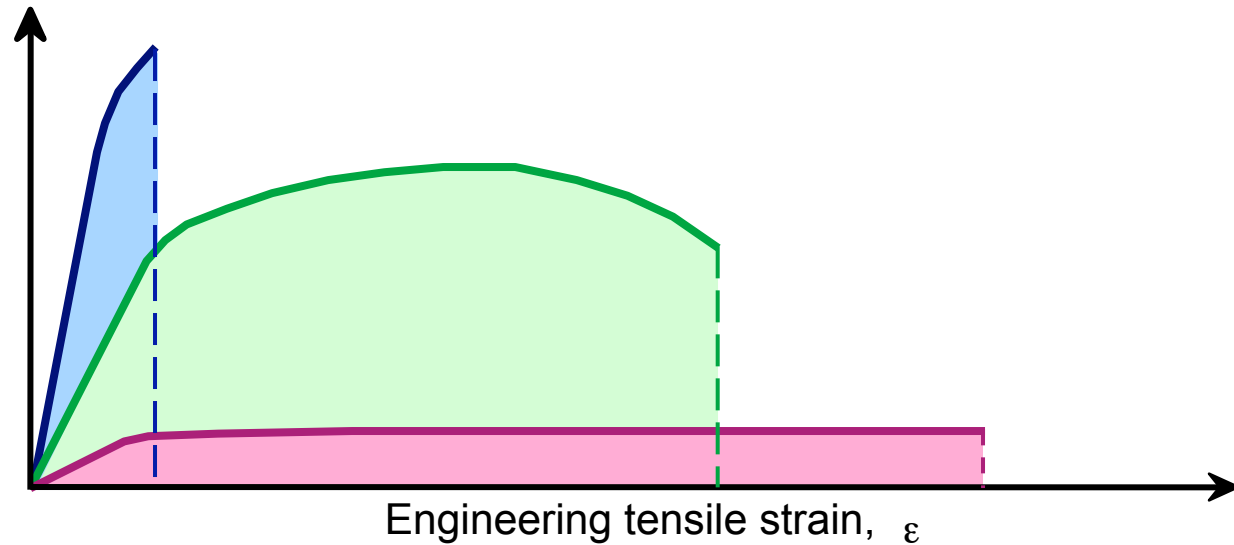


Toughness

- Energy to break a unit volume of material
- Approximate by the area under the stress-strain curve.

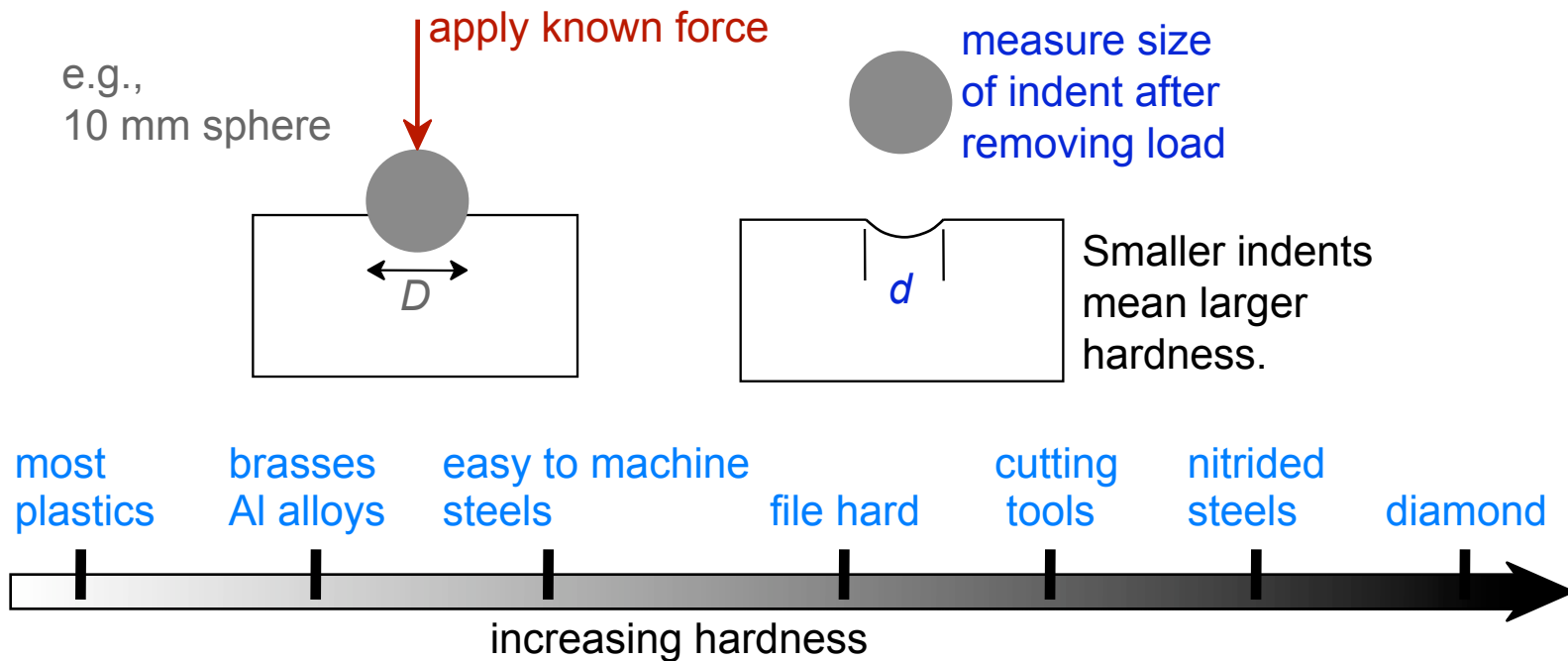
Engineering
tensile
stress, σ

Adapted from Fig. 6.13,
Callister 7e.



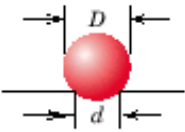
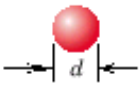
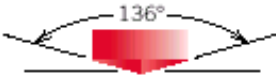
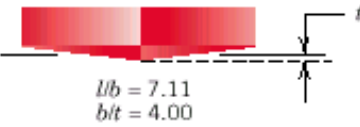
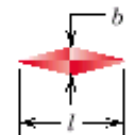
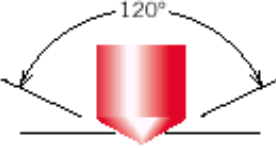
Hardness

- Resistance to permanently indenting the surface.
- Large hardness means:
 - resistance to plastic deformation or cracking in compression.
 - better wear properties.



Hardness Measurement

Table 6.5 Hardness Testing Techniques

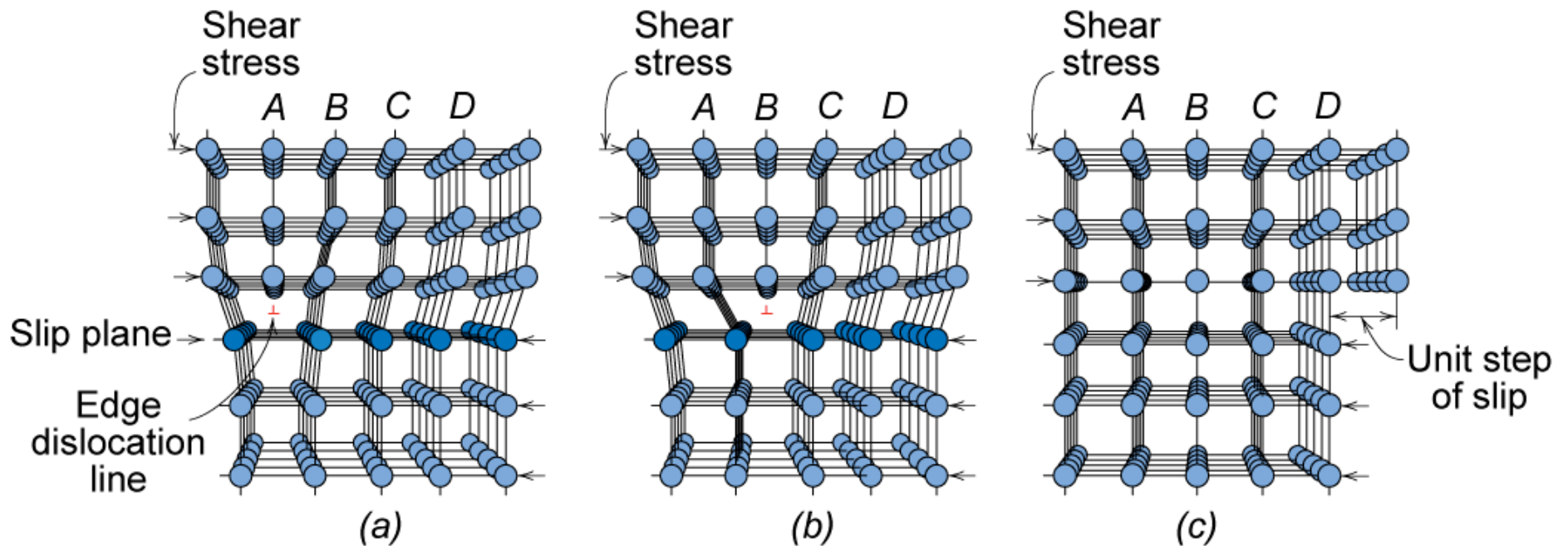
Test	Indenter	Shape of Indentation		Load	Formula for Hardness Number ^a
		Side View	Top View		
Brinell	10-mm sphere of steel or tungsten carbide			P	$HB = \frac{2P}{\pi D[D - \sqrt{D^2 - d^2}]}$
Vickers microhardness	Diamond pyramid			P	$HV = 1.854P/d_1^2$
Knoop microhardness	Diamond pyramid			P	$HK = 14.2P/l^2$
Rockwell and Superficial Rockwell	Diamond cone $\frac{1}{16}, \frac{1}{8}, \frac{1}{4}, \frac{1}{2}$ in. diameter steel spheres	 	 	60 kg 100 kg 150 kg } Rockwell 15 kg 30 kg 45 kg } Superficial Rockwell	

^a For the hardness formulas given, P (the applied load) is in kg, while D , d , d_1 , and l are all in mm.

Source: Adapted from H. W. Hayden, W. G. Moffatt, and J. Wulff, *The Structure and Properties of Materials*, Vol. III, *Mechanical Behavior*. Copyright © 1965 by John Wiley & Sons, New York. Reprinted by permission of John Wiley & Sons, Inc.

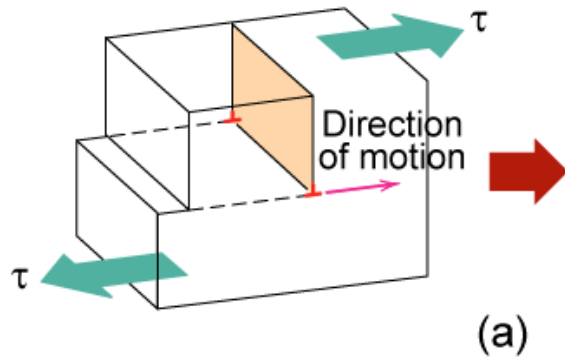
Dislocation and plastic deformation

- Cubic & hexagonal metals - plastic deformation by **plastic shear or slip** where one plane of atoms slides over adjacent plane by defect motion (dislocations).



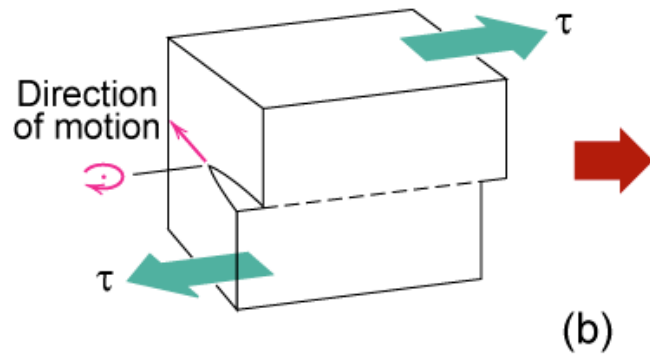
Adapted from Fig. 7.1,
Callister 7e.

Dislocation motion



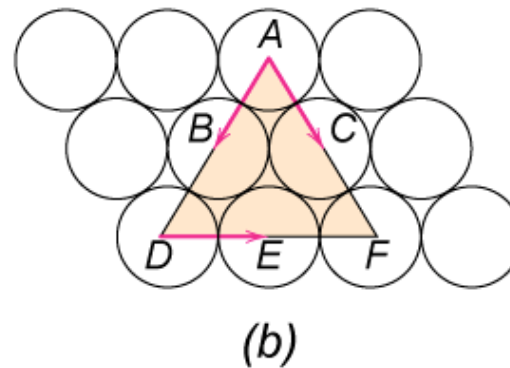
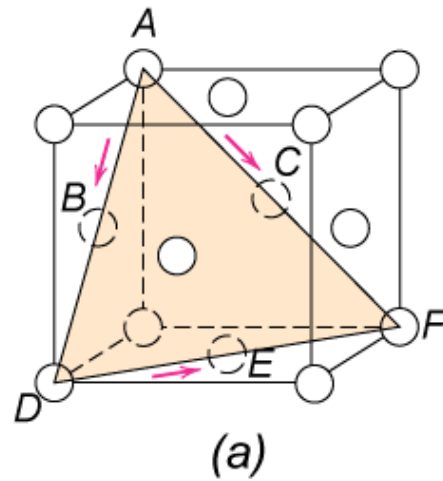
Edge dislocation

Adapted from Fig. 7.2,
Callister 7e.



Screw dislocation

Deformation mechanisms

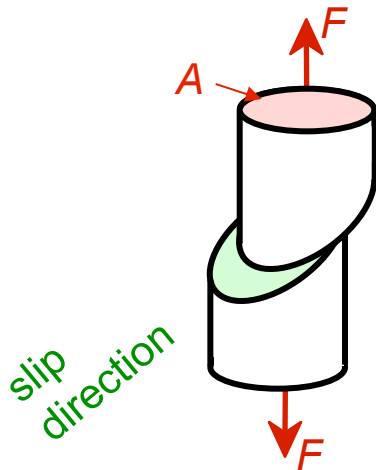


Adapted from Fig. 7.6, *Callister 7e*.

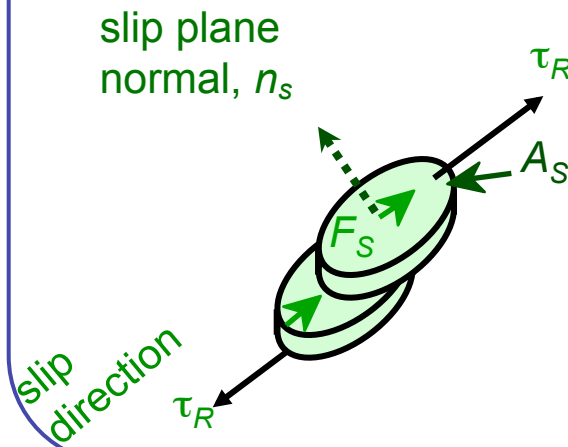
Slip in single crystals

- Crystals slip due to a **resolved shear stress**, τ_R .
- Applied tension can produce such a stress.

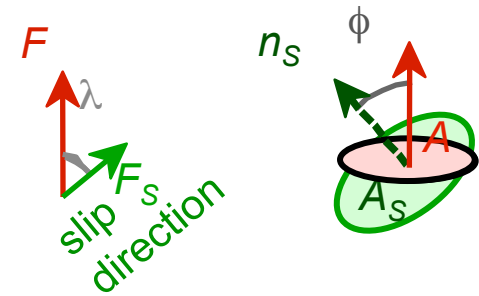
Applied **tensile** stress:



Resolved shear stress:

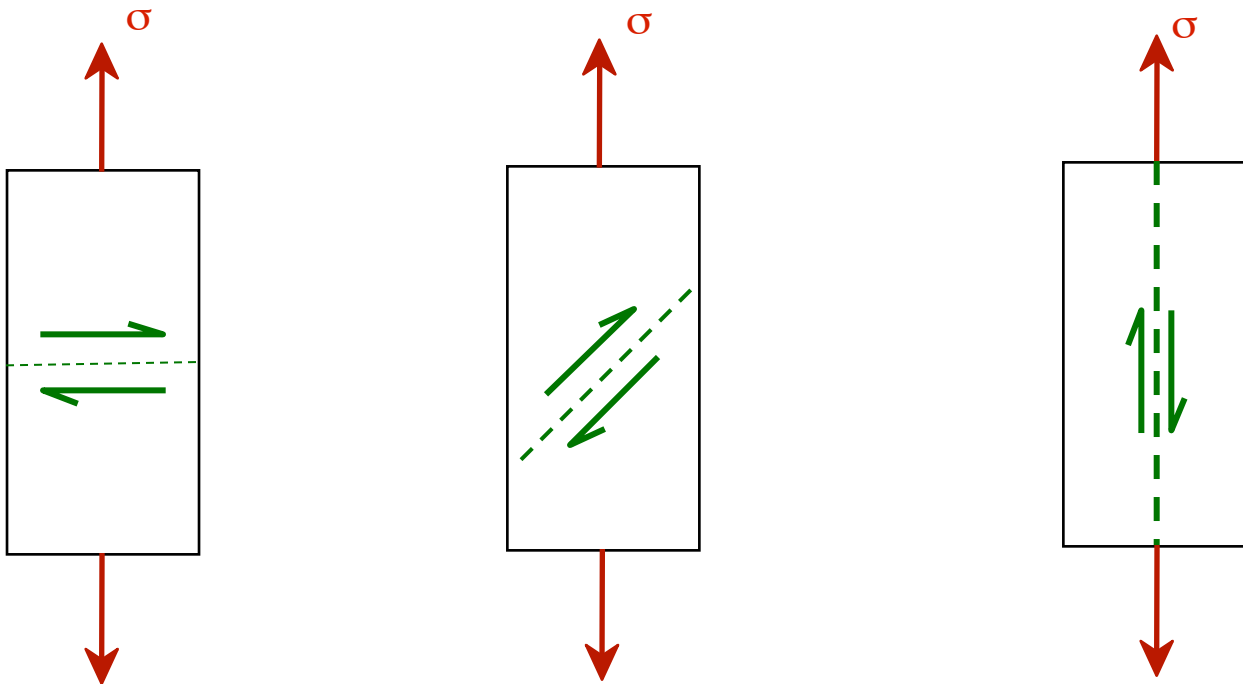


Relation between σ and τ_R



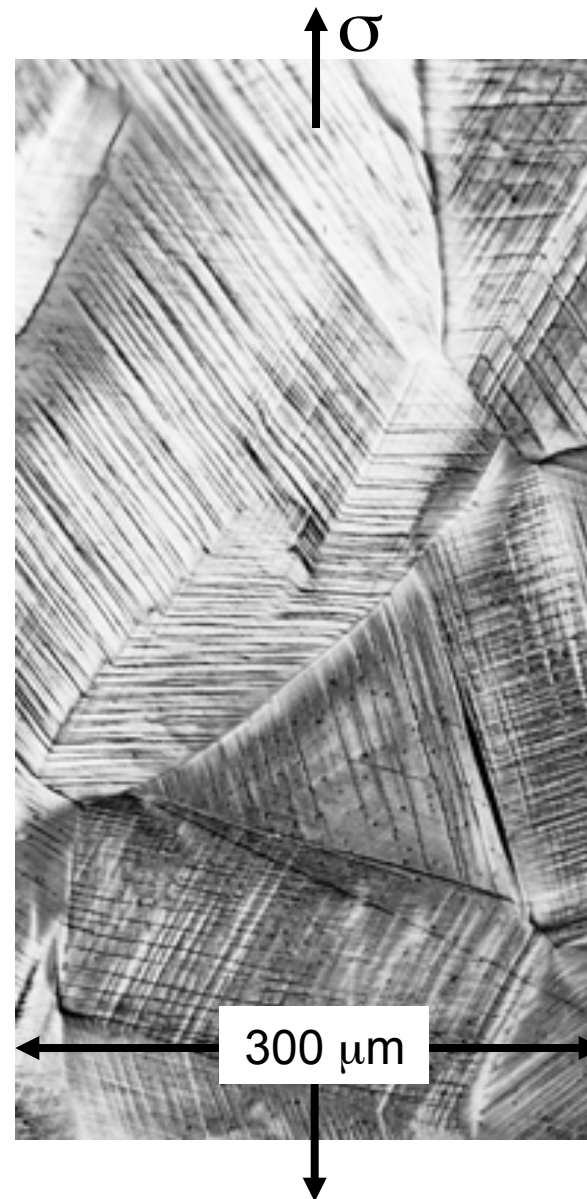
Critical resolved shear stress

- Condition for dislocation motion:
- Crystal orientation can make it easy or hard to move dislocation



Slip motion in polycrystals

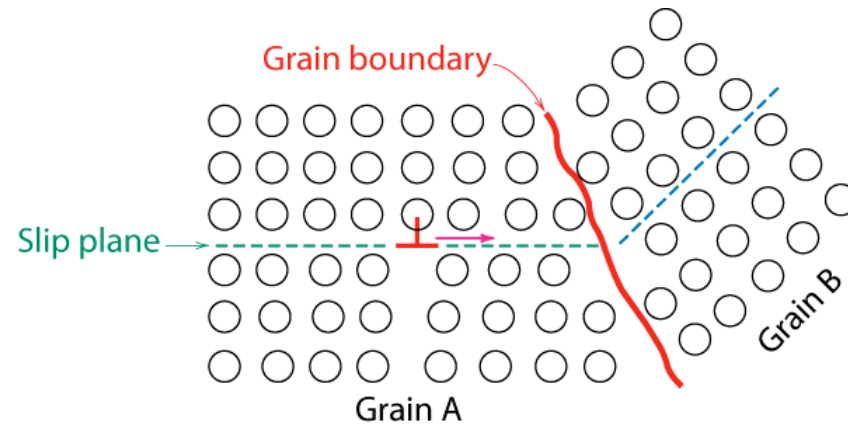
- Stronger - grain boundaries pin deformations
- Slip planes & directions (λ , ϕ) change from one crystal to another.
- τ_R will vary from one crystal to another.
- The crystal with the largest τ_R yields first.
- Other (less favorably oriented) crystals yield later.



Adapted from Fig. 7.10, *Callister 7e*. (Fig. 7.10 is courtesy of C. Brady, National Bureau of Standards [now the National Institute of Standards and Technology, Gaithersburg, MD].)

Strategies for strengthening: grain size reduction

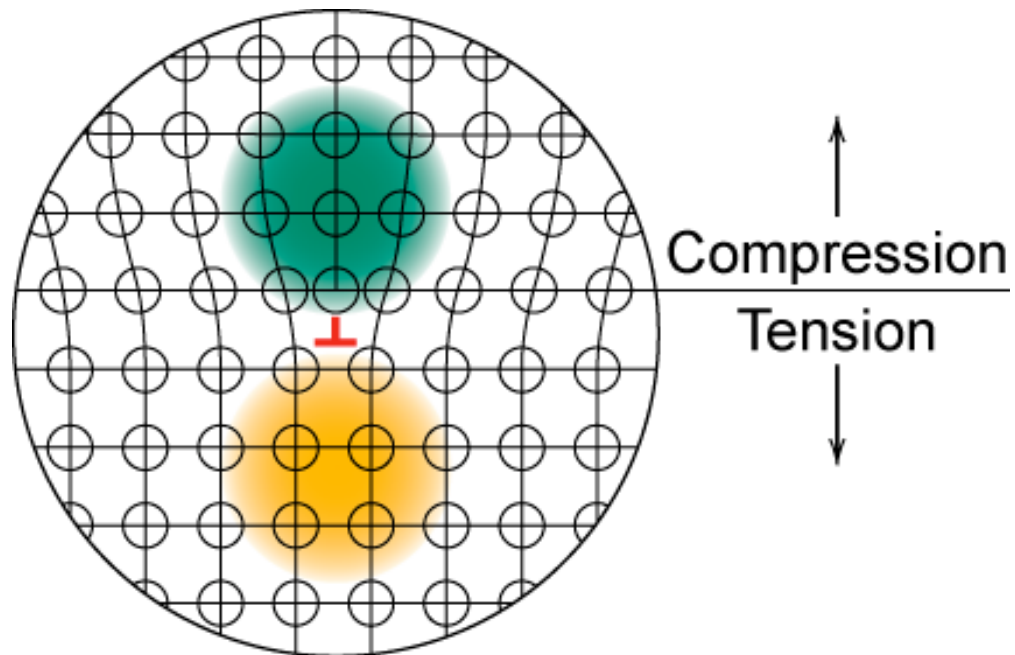
- Grain boundaries are barriers to slip.
- Barrier "strength" increases with increasing angle of misorientation.
- Smaller grain size: more barriers to slip.



Adapted from Fig. 7.14, *Callister 7e*.
(Fig. 7.14 is from *A Textbook of Materials Technology*, by Van Vlack, Pearson Education, Inc., Upper Saddle River, NJ.)

- Hall-Petch Equation:

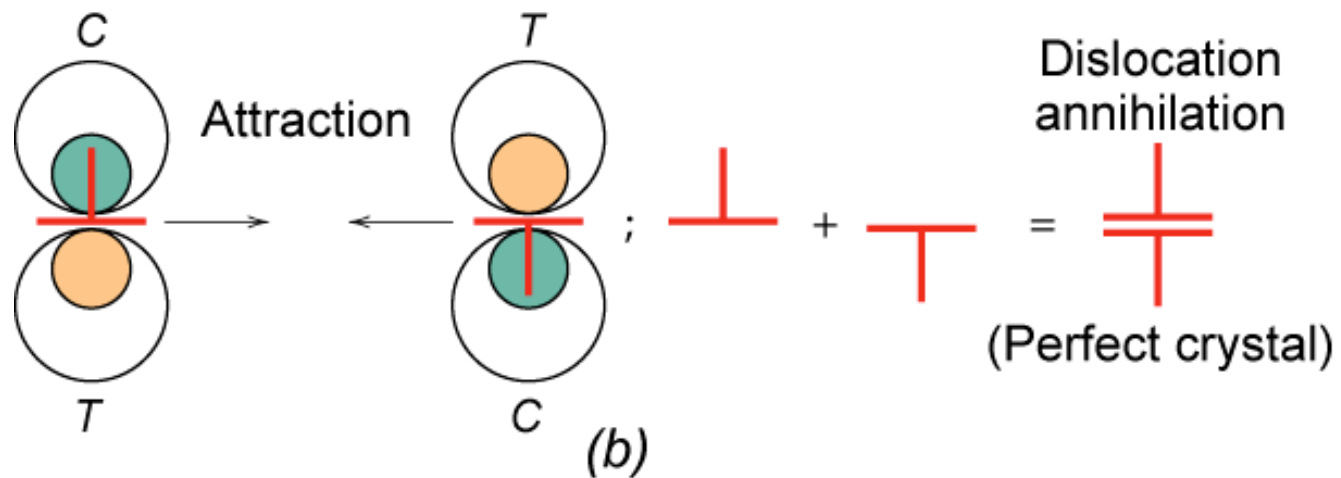
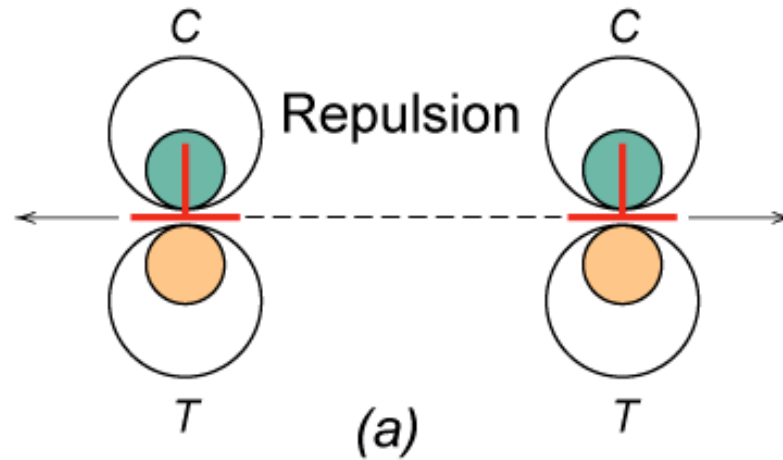
Strategies for strengthening: solid solutions



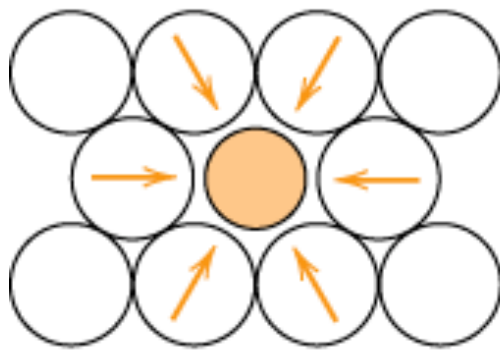
Adapted from Fig. 7.4,
Callister 7e.

Effects of stress at dislocations

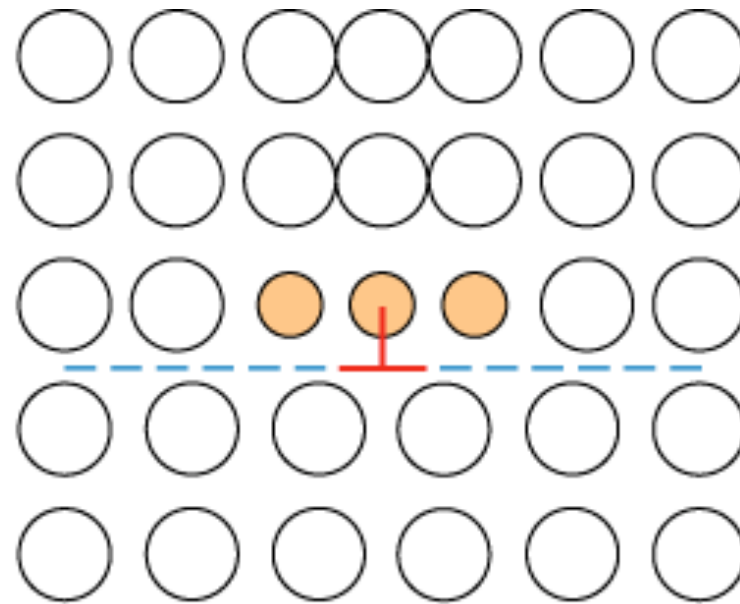
Adapted from Fig.
7.5, Callister 7e.



Strengthening by alloying



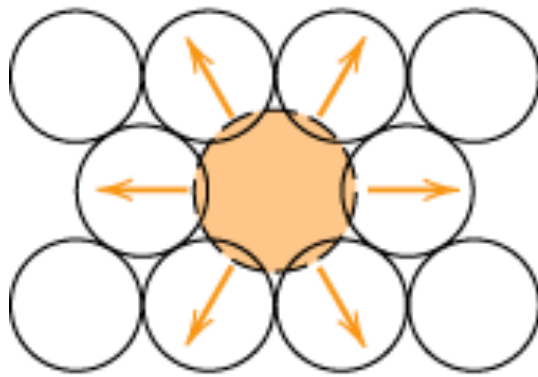
(a)



(b)

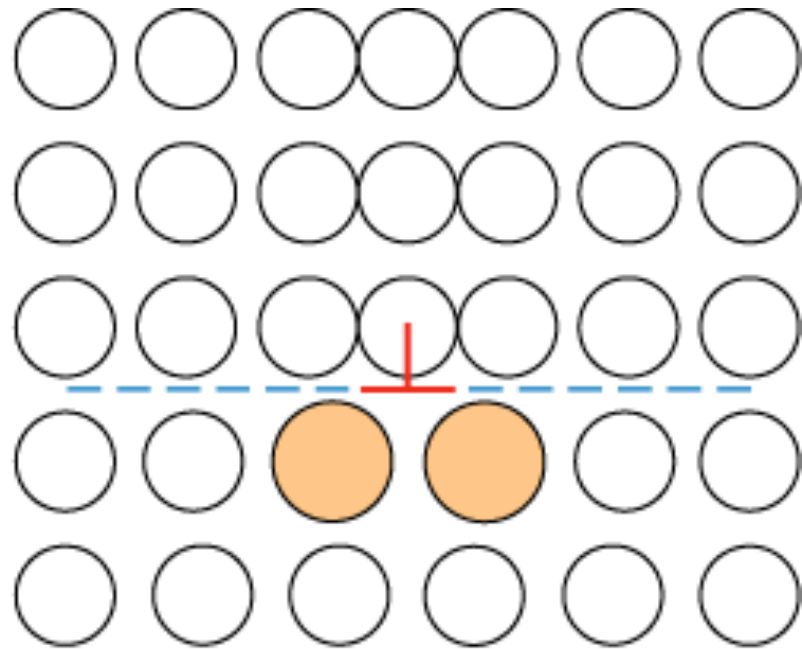
Adapted from Fig.
7.17, *Callister 7e*.

Strengthening by alloying



(a)

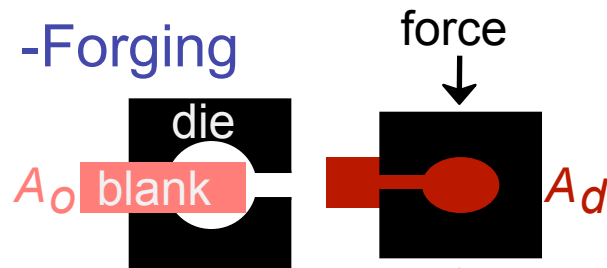
Adapted from Fig.
7.18, *Callister 7e*.



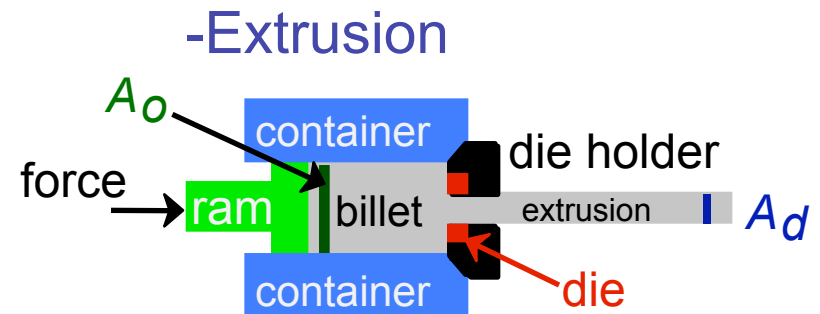
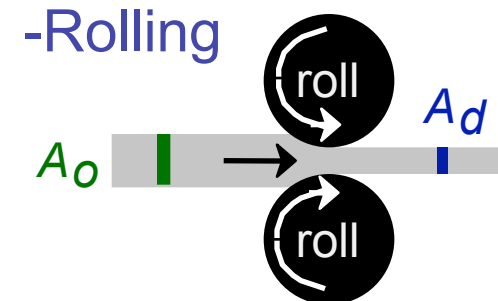
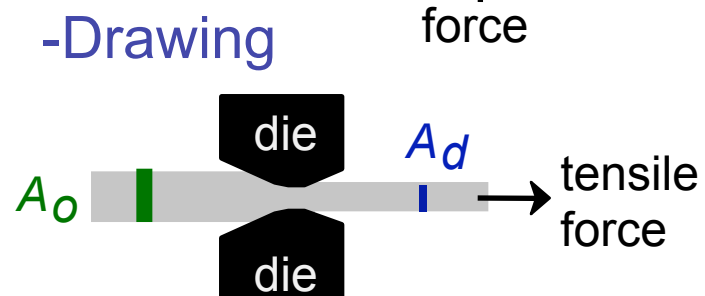
(b)

Strategies for strengthening: Cold work (%CW)

- Room temperature deformation.
- Common forming operations change the cross sectional area:

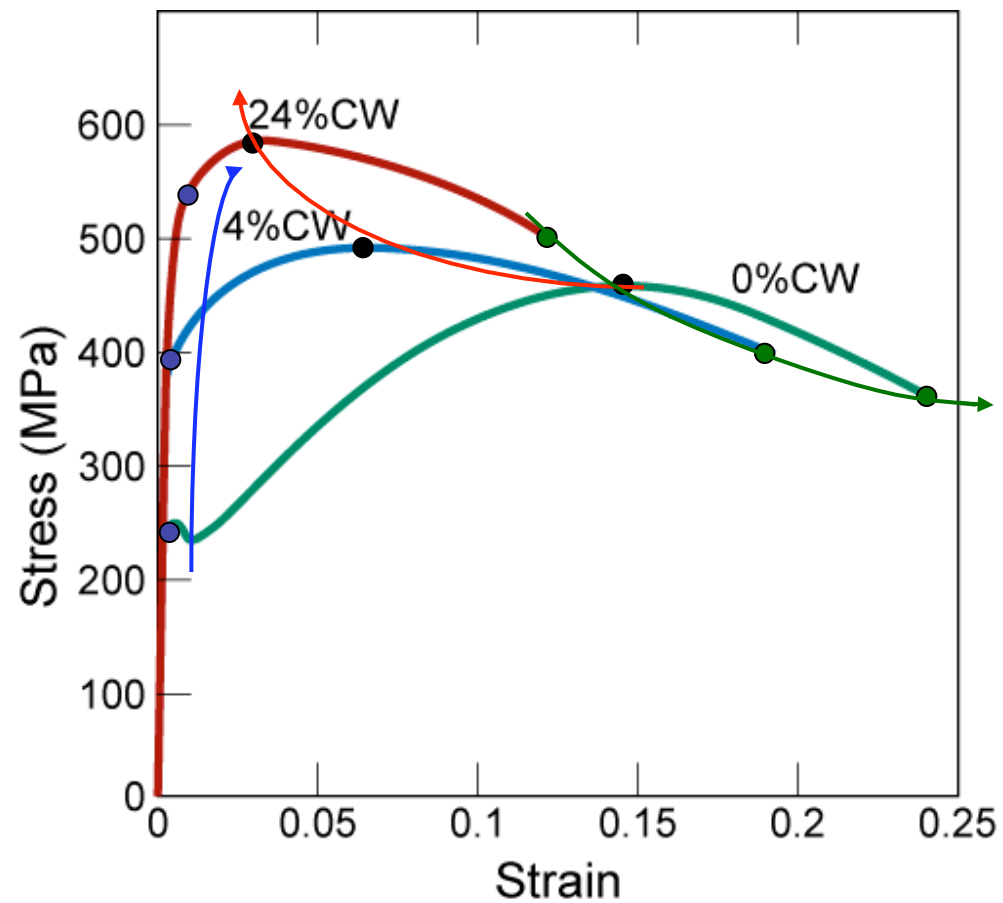


Adapted from Fig. 11.8, Callister 7e.



Impact of cold work

As cold work is increased



Adapted from Fig. 7.20,
Callister 7e.